

Customer Information Notification

Issue Date: 29-Mar-2020 Effective Date: 30-Mar-2020 Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP. For detailed information we invite you to <u>view this</u> notification online

This notice is NXP Company Proprietary.

2020030301



QUALITY

| Change Category | | | |
|--------------------------|--|------------------------|---|
| [] Wafer Fab Process | [] Assembly[] Product Marking Process | [] Test Location | [] Design |
| [] Wafer Fab Materials | [] Assembly[] Mechanical Materials Specification | []Test Process | [] Errata |
| [] Wafer Fab Location | [] Assembly[] Location Packing/Shipping/Labeling | [] Test g Equipment | [] Electrical spec./Test coverage |
| [] Firmware | [X] Other - Data Sheet Update - Ordering Information and Corrections | | |
| PF8121 Data Sheet | | | |
| Update to Rev 3.0 | | | |
| Ördering Information and | | | |
| Corrections) | | | |

Description

NXP Semiconductors announces the data sheet update to revision 3.0 for the PF8121 Power Management IC devices associated with this notification. The revision history included in the updated document provides a detailed description of the changes. Changes are summarized below.

PF8121 rev 3.0 Data Sheet Updates:

Table 2 Ordering information

1. Add new orderable part number MC32PF8121G5EP

2. Correct comments / nomenclature for part number MC32PF8121EUEP (replaced BUCK7 by SW7, and BUCK3 by SW4)

** Documentation change only for customer clarifications - absolutely no changes to the device / product **

The new PF8121 rev 3.0 data sheet is attached to this notification, and may be obtained from NXP.com:

https://www.nxp.com/docs/en/data-sheet/PF8121.pdf

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02 Reason

The data sheet has been updated to include new orderable part number, and provide corrections / clarifications regarding part number MC32PF8121EUEP system comments.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Additional information

Affected products and sales history information: see attached file

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please <u>contact NXP "Global Quality</u> <u>Support Team"</u>.

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly: **Name** Joaquin Romo

Position System and Applications Engineer

e-mail address joaquin.romo@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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